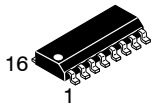
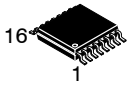
8-Bit Shift Register with Output Storage Register

(3-State)

MC74VHC595



SOIC−16
D SUFFIX
CASE 751B



TSSOP−16
DT SUFFIX
CASE 948F

QFN16
MN SUFFIX
CASE 485AW

The MC74VHC595 is an advanced high speed 8−bit shift register with an output storage register fabricated with silicon gate CMOS technology.

It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The MC74VHC595 contains an 8−bit static shift register which feeds an 8−bit storage register.

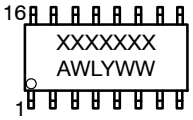
Shift operation is accomplished on the positive going transition of the Shift Clock input (SCK). The output register is loaded with the contents of the shift register on the positive going transition of the Register Clock input (RCK). Since the RCK and SCK signals are independent, parallel outputs can be held stable during the shift operation. And, since the parallel outputs are 3−state, the VHC595 can be directly connected to an 8−bit bus. This register can be used in serial−to−parallel conversion, data receivers, etc.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output. The inputs tolerate voltages up to 5.5 V, allowing the interface of 5 V systems to 3 V systems.

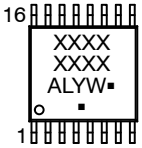
Features

- High Speed: f_{max} = 185 MHz (Typ) at V_{CC} = 5 V
- Low Power Dissipation: I_{CC} = 4 μA (Max) at T_A = 25°C
- High Noise Immunity: $V_{NIH} = V_{NIL}$ = 28% V_{CC}
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Designed for 2 V to 5.5 V Operating Range
- Low Noise: V_{OLP} = 1.0 V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance: HBM > 2000 V; Machine Model > 200 V
- −Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable
- These Devices are Pb−Free and are RoHS Compliant

MARKING DIAGRAMS



SOIC−16



TSSOP−16

QFN16

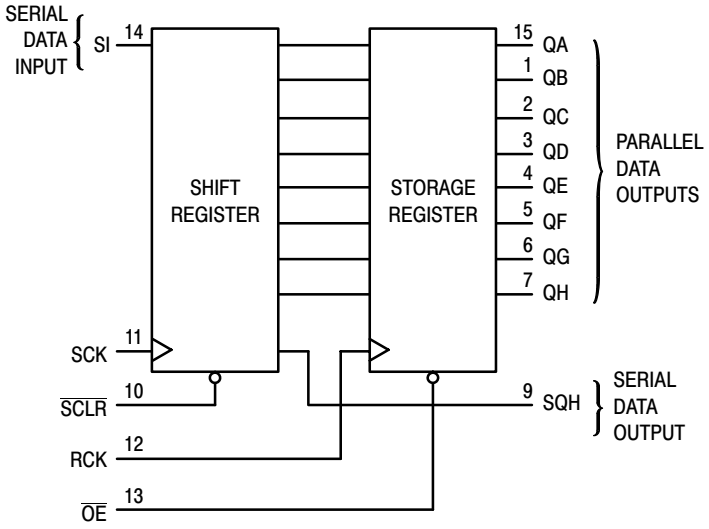
XXXXXXX = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or ▪ = Pb−Free Package

(Note: Microdot may be in either location)

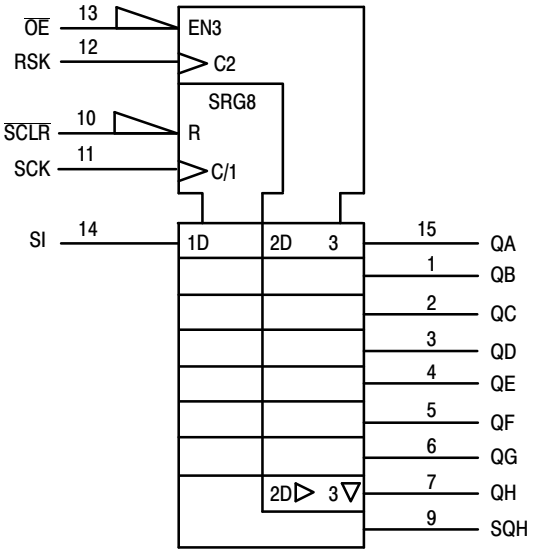
ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 10 of this data sheet.

LOGIC DIAGRAM



IEC LOGIC SYMBOL



FUNCTION TABLE

Operation	Inputs					Resulting Function			
	Reset ($\overline{SCLR}$)	Serial Input (SI)	Shift Clock (SCK)	Reg Clock (RCK)	Output Enable ($\overline{OE}$)	Shift Register Contents	Storage Register Contents	Serial Output (SQH)	Parallel Outputs (QA – QH)
Clear shift register	L	X	X	L, H, ↓	L	L	U	L	U
Shift data into shift register	H	D	↑	L, H, ↓	L	$D \rightarrow SR_A$; $SR_N \rightarrow SR_{N+1}$	U	$SR_G \rightarrow SR_H$	U
Registers remains unchanged	H	X	L, H, ↓	X	L	U	**	U	**
Transfer shift register contents to storage register	H	X	L, H, ↓	↑	L	U	$SR_N \rightarrow STR_N$	*	SR_N
Storage register remains unchanged	X	X	X	L, H, ↓	L	*	U	*	U
Enable parallel outputs	X	X	X	X	L	*	**	*	Enabled
Force outputs into high impedance state	X	X	X	X	H	*	**	*	Z

SR = shift register contents D = data (L, H) logic level ↓ = High−to−Low * = depends on Reset and Shift Clock inputs
STR = storage register contents U = remains unchanged ↑ = Low−to−High ** = depends on Register Clock input

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +6.5	V
V_{IN}	DC Input Voltage		−0.5 to +6.5	V
V_{OUT}	DC Output Voltage		−0.5 to V_{CC}+0.5	V
I_{IN}	DC Input Current, per Pin		±20	mA
I_{OUT}	DC Output Current, per Pin		±25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins		±50	mA
I_{IK}	Input Clamp Current		−20	mA
I_{OK}	Output Clamp Current		±20	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SOIC−16 QFN16 TSSOP−16	126 118 159	°C/W
P_D	Power Dissipation in Still Air at 25°C	SOIC−16 QFN16 TSSOP−16	995 1062 787	mW
MSL	Moisture Sensitivity		Level 1	−
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in.	−
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri−stated.
2. Measured with minimum pad spacing on an FR4 board, using 76mm−by−114mm, 2−ounce copper trace no air flow per JESD51−7.
3. HBM tested to EIA / JESD22−A114−A. CDM tested to JESD22−C101−A. JEDEC recommends that ESD qualification to EIA/JESD22−A115A (Machine Model) be discontinued.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	DC Supply Voltage		2.0	5.5	V
V_{IN}	DC Input Voltage (Note 4)		0	5.5	V
V_{OUT}	DC Output Voltage (Note 4)		0	V_{CC}	V
T_A	Operating Temperature		–55	+125	°C
t_r, t_f	Input Rise or Fall Rate	V_{CC} = 3.0 V to 3.6 V V_{CC} = 4.5 V to 5.5 V	0 0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V_{CC} (V)	T_A = 25°C			T_A = ≤ 85°C		T_A = ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V_{IH}	Minimum High–Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85			1.5 2.1 3.15 3.85		1.5 2.1 3.15 3.85		V
V_{IL}	Maximum Low–Level Input Voltage		2.0 3.0 4.5 5.5			0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65	V
V_{OH}	Minimum High–Level Output Voltage V_{IN} = V_{IH} or V_{IL}	V_{IN} = V_{IH} or V_{IL} I_{OH} = – 50 μA	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		V_{IN} = V_{IH} or V_{IL} I_{OH} = –4 mA I_{OH} = –8 mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V_{OL}	Maximum Low–Level Output Voltage V_{IN} = V_{IH} or V_{IL}	V_{IN} = V_{IH} or V_{IL} I_{OL} = 50 μA	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		V_{IN} = V_{IH} or V_{IL} I_{OL} = 4 mA I_{OL} = 8 mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I_{IN}	Maximum Input Leakage Current	V_{IN} = 5.5 V or GND	0 to 5.5			± 0.1		± 1.0		± 1.0	μA
I_{CC}	Maximum Quiescent Supply Current	V_{IN} = V_{CC} or GND	5.5			4.0		40.0		40.0	μA
I_{OZ}	Three–State Output Off–State Current	V_{IN} = V_{IH} or V_{IL} V_{OUT} = V_{CC} or GND	5.5			± 0.25		± 2.5		± 2.5	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	T_A = 25°C			T_A = ≤ 85°C		T_A = ≤ 125°C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
f_{max}	Maximum Clock Frequency (50% Duty Cycle)	V_{CC} = 3.3 ± 0.3 V	80	150		70		70		MHz
		V_{CC} = 5.0 ± 0.5 V	135	185		115		115		
t_{PLH}, t_{PHL}	Propagation Delay, SCK to SQH	V_{CC} = 3.3 ± 0.3 V C_L = 15pF		8.8	13.0	1.0	15.0	1.0	15.0	ns
		V_{CC} = 3.3 ± 0.3 V C_L = 50pF		11.3	16.5	1.0	18.5	1.0	18.5	
		V_{CC} = 5.0 ± 0.5 V C_L = 15pF		6.2	8.2	1.0	9.4	1.0	9.4	
		V_{CC} = 5.0 ± 0.5 V C_L = 50pF		7.7	10.2	1.0	11.4	1.0	11.4	
t_{PHL}	Propagation Delay, $\overline{CPLR}$ to SQH	V_{CC} = 3.3 ± 0.3 V C_L = 15pF		8.4	12.8	1.0	13.7	1.0	13.7	ns
		V_{CC} = 3.3 ± 0.3 V C_L = 50pF		10.9	16.3	1.0	17.2	1.0	17.2	
		V_{CC} = 5.0 ± 0.5 V C_L = 15pF		5.9	8.0	1.0	9.1	1.0	9.1	
		V_{CC} = 5.0 ± 0.5 V C_L = 50pF		7.4	10.0	1.0	11.1	1.0	11.1	
t_{PLH}, t_{PHL}	Propagation Delay, RCK to QA−QH	V_{CC} = 3.3 ± 0.3 V C_L = 15pF		7.7	11.9	1.0	13.5	1.0	13.5	ns
		V_{CC} = 3.3 ± 0.3 V C_L = 50pF		10.2	15.4	1.0	17.0	1.0	17.0	
		V_{CC} = 5.0 ± 0.5 V C_L = 15pF		5.4	7..4	1.0	8.5	1.0	8.5	
		V_{CC} = 5.0 ± 0.5 V C_L = 50pF		6.9	9.4	1.0	10.5	1.0	10.5	
t_{PZL}, t_{PZH}	Output Enable Time, $\overline{OE}$ to QA−QH	V_{CC} = 3.3 ± 0.3 V C_L = 15pF		7.5	11.5	1.0	13.5	1.0	13.5	ns
		V_{CC} = 3.3 ± 0.3 V C_L = 50pF		9.0	15.0	1.0	17.0	1.0	17.0	
		V_{CC} = 5.0 ± 0.5 V C_L = 15pF		4.8	8.6	1.0	10.0	1.0	10.0	
		V_{CC} = 5.0 ± 0.5 V C_L = 50pF		8.3	10.6	1.0	12.0	1.0	12.0	
t_{PLZ}, t_{PHZ}	Output Disable Time, $\overline{OE}$ to QA−QH	V_{CC} = 3.3 ± 0.3 V C_L = 50pF		12.1	15.7	1.0	16.2	1.0	16.2	ns
		V_{CC} = 5.0 ± 0.5 V C_L = 50pF		7.6	10.3	1.0	11.0	1.0	11.0	
C_{IN}	Input Capacitance			4	10		10		10	pF
C_{OUT}	Three−State Output Capacitance (Output in High−Impedance State), QA−QH			6			10		10	pF

		Typical @ 25°C, V_{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Note 5)	87	pF

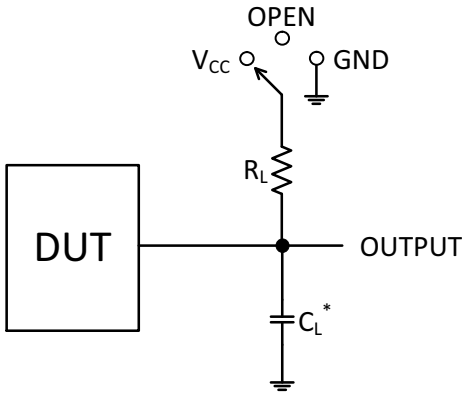
5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no−load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

NOISE CHARACTERISTICS (C_L = 50 pF, V_{CC} = 5.0 V)

Symbol	Characteristic	T_A = 25°C		Unit
		Typ	Max	
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	0.8	1.0	V
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	−0.8	−1.0	V
V_{IHD}	Minimum High Level Dynamic Input Voltage		3.5	V
V_{ILD}	Maximum Low Level Dynamic Input Voltage		1.5	V

TIMING REQUIREMENTS

Symbol	Parameter	V_{CC} V	T_A = 25°C		T_A = − 40 to 85°C	T_A = − 55 to 125°C	Unit
			Typ	Limit	Limit	Limit	
t_{su}	Setup Time, SI to SCK	3.3 5.0		3.5 3.0	3.5 3.0	3.5 3.0	ns
$t_{su(H)}$	Setup Time, SCK to RCK	3.3 5.0		8.0 5.0	8.5 5.0	8.5 5.0	ns
$t_{su(L)}$	Setup Time, $\overline{SCLR}$ to RCK	3.3 5.0		8.0 5.0	9.0 5.0	9.0 5.0	ns
t_h	Hold Time, SI to SCK	3.3 5.0		1.5 2.0	1.5 2.0	1.5 2.0	ns
$t_{h(L)}$	Hold Time, $\overline{SCLR}$ to RCK	3.3 5.0		0 0	0 0	1.0 1.0	ns
t_{rec}	Recovery Time, $\overline{SCLR}$ to SCK	3.3 5.0		3.0 2.5	3.0 2.5	3.0 2.5	ns
t_w	Pulse Width, SCK or RCK	3.3 5.0		5.0 5.0	5.0 5.0	5.0 5.0	ns
$t_{w(L)}$	Pulse Width, $\overline{SCLR}$	3.3 5.0		5.0 5.0	5.0 5.0	5.0 5.0	ns



Test	Switch Position	C_L	R_L
t_{PLH} / t_{PHL}	Open	See AC Characteristics Table	1 kΩ
t_{PLZ} / t_{PZL}	V_{CC}		
t_{PHZ} / t_{PZH}	GND		

*C_L Includes probe and jig capacitance
Input $t_R = t_F$ = 3 ns

Figure 1. Test Circuit

SWITCHING WAVEFORMS

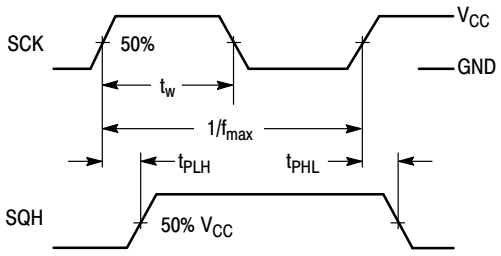


Figure 2.

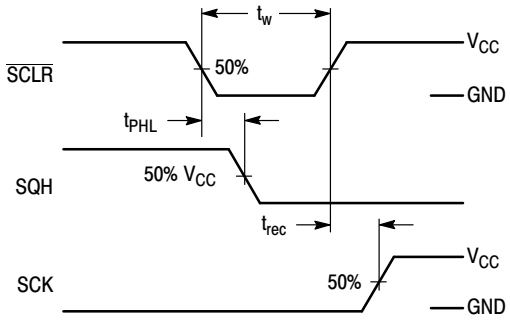


Figure 3.

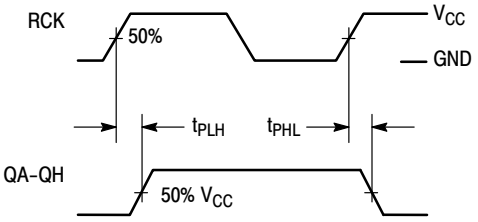


Figure 4.

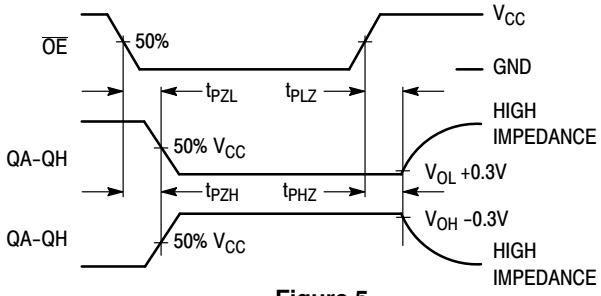


Figure 5.

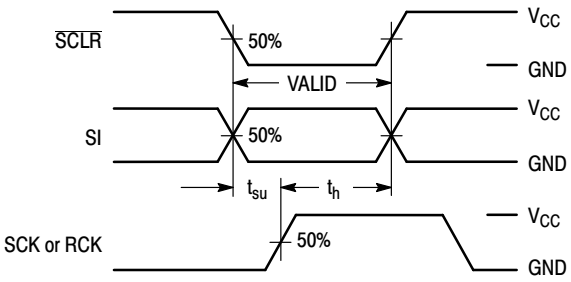


Figure 6.

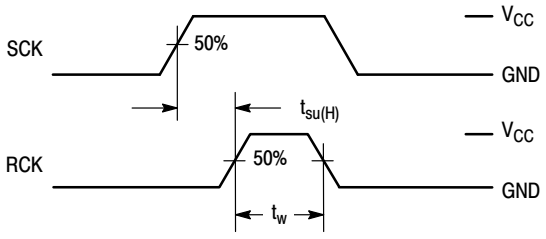


Figure 7.

EXPANDED LOGIC DIAGRAM

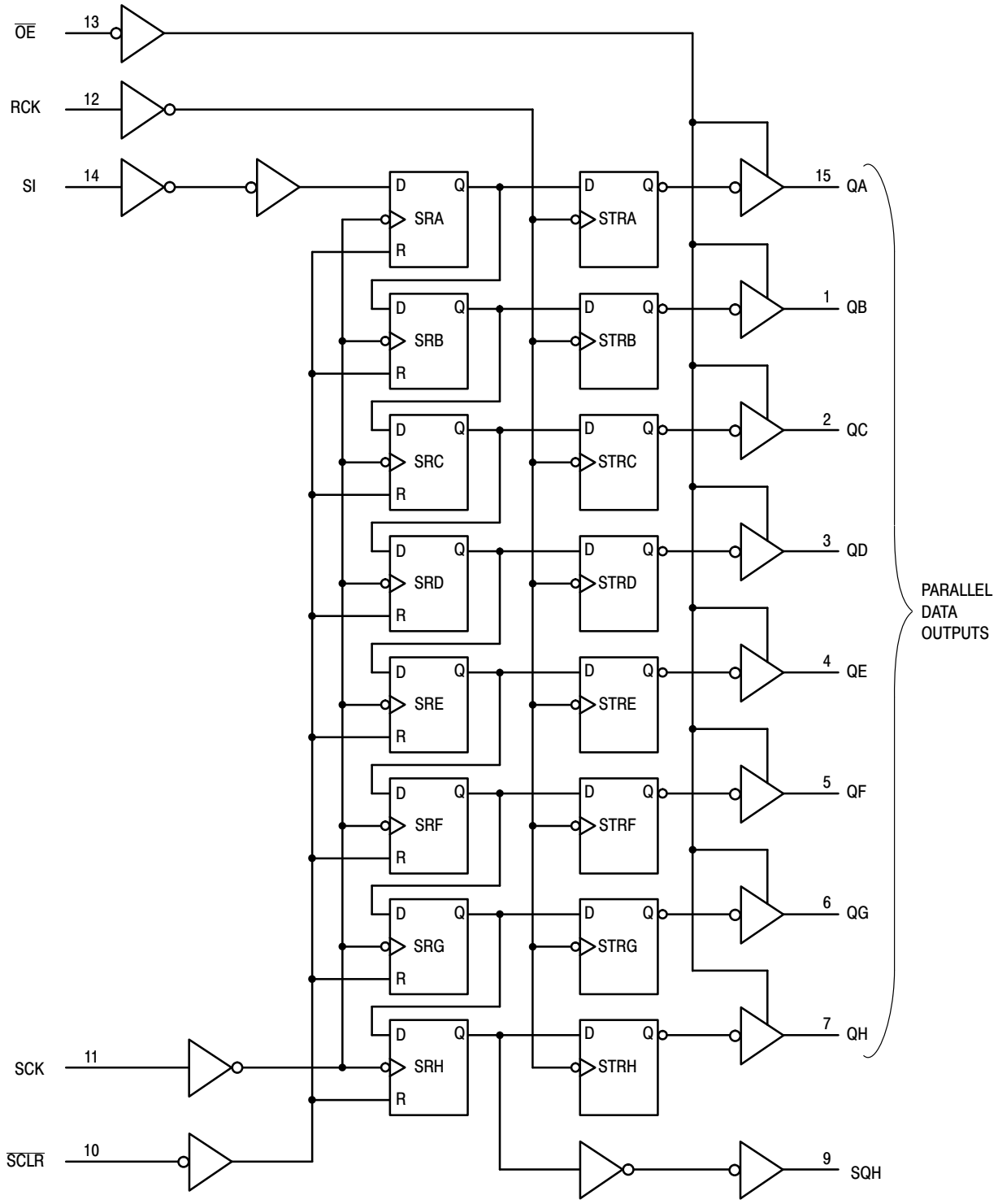
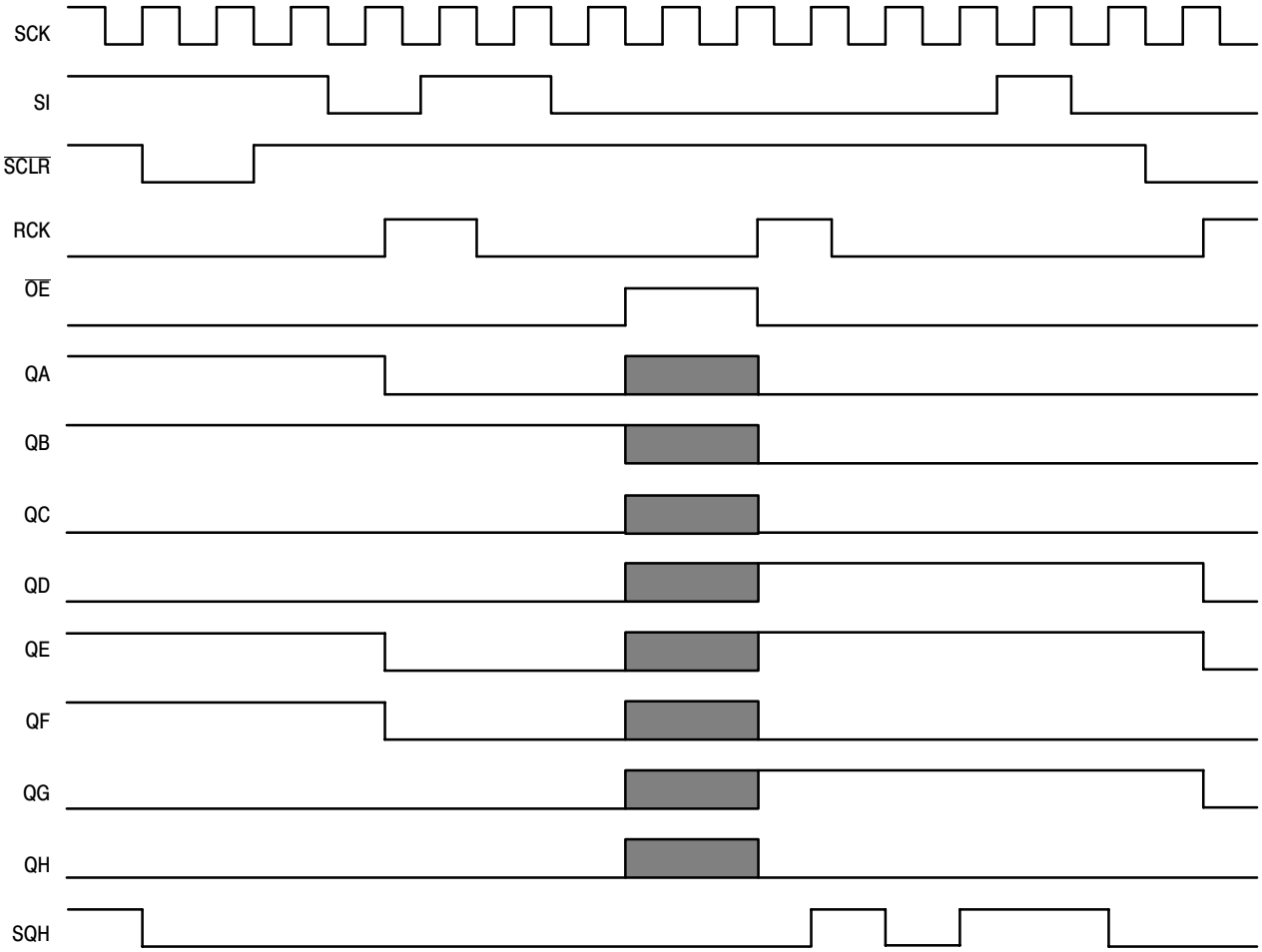


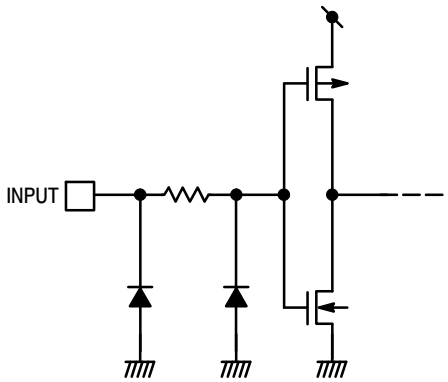
Figure 8.

TIMING DIAGRAM



NOTE: output is in a high−impedance state.

INPUT EQUIVALENT CIRCUIT



ORDERING INFORMATION

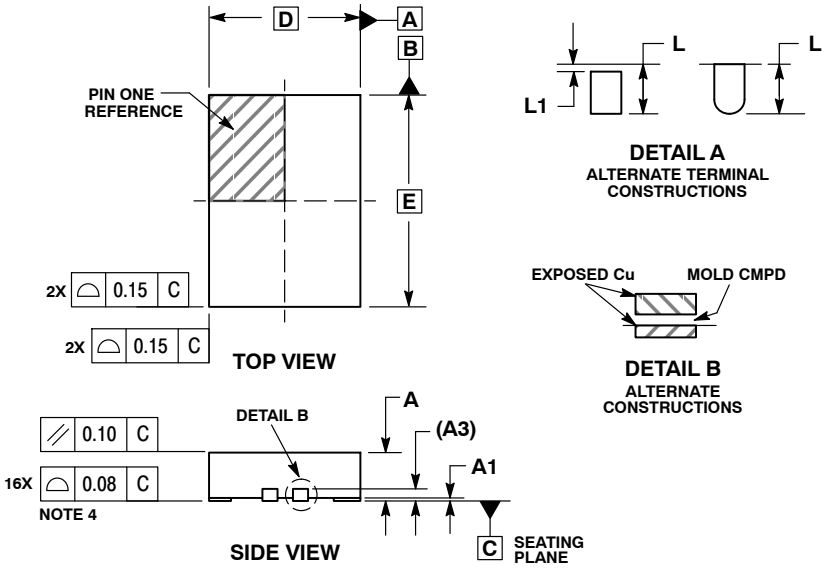
Device	Marking	Package	Shipping†
MC74VHC595DR2G	VHC595G	SOIC−16	2500 Units / Tape & Reel
MC74VHC595DTR2G	VHC 595	TSSOP−16	2500 Units / Tape & Reel
MC74VHC595DTR2G−Q*	VHC 595	TSSOP−16	2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*−Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable.

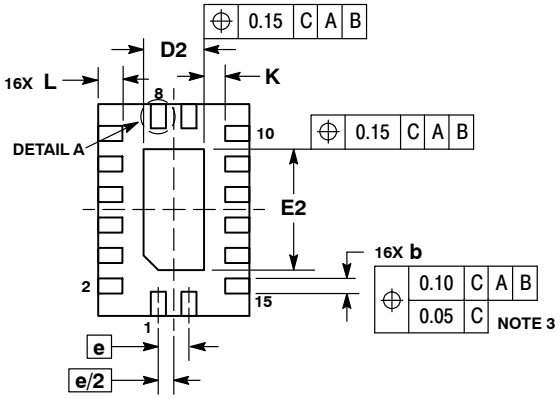
PACKAGE DIMENSIONS

QFN16, 2.5x3.5, 0.5P
CASE 485AW
ISSUE O

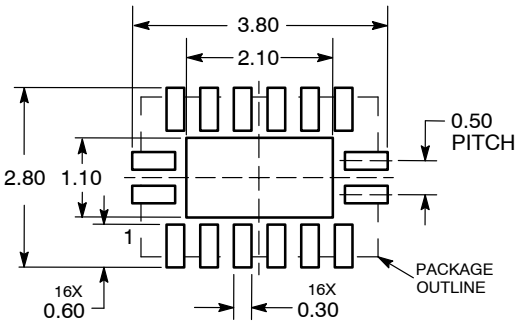


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.50 BSC	
D2	0.85	1.15
E	3.50 BSC	
E2	1.85	2.15
e	0.50 BSC	
K	0.20	---
L	0.35	0.45
L1	---	0.15



RECOMMENDED SOLDERING FOOTPRINT*

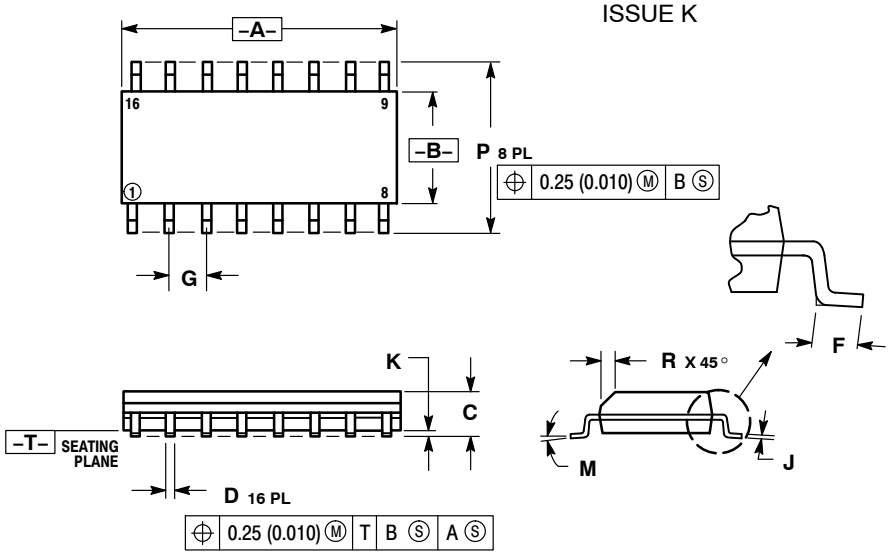


DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

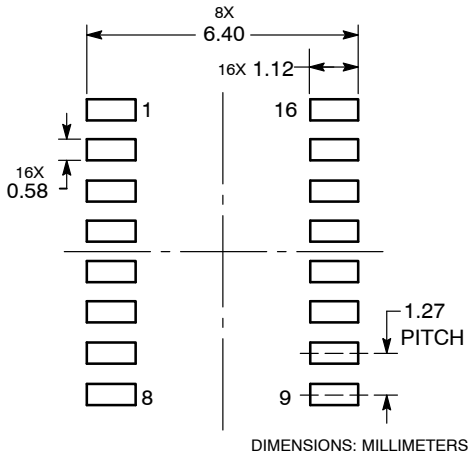
SOIC−16
CASE 751B−05
ISSUE K



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

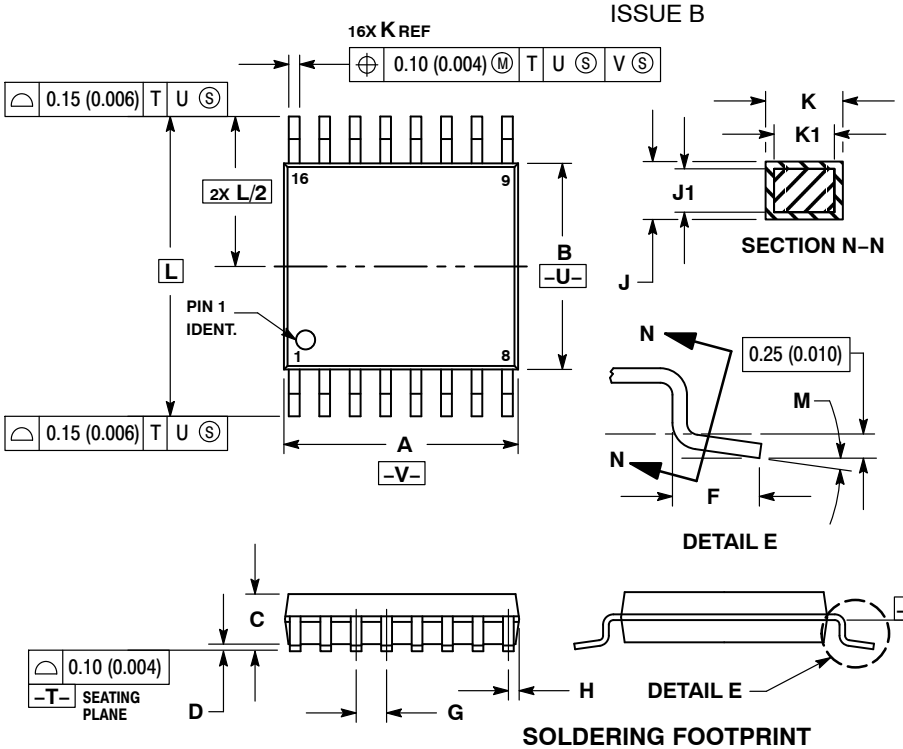
SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

PACKAGE DIMENSIONS

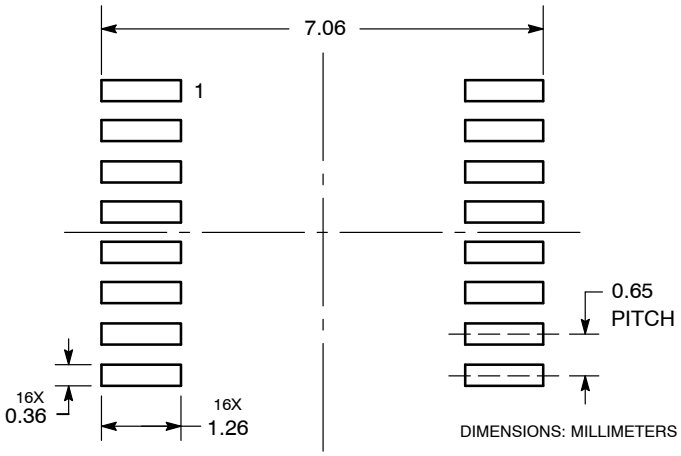
TSSOP−16
CASE 948F
ISSUE B



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	−−−	1.20	−−−	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

SOLDERING FOOTPRINT



ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
Technical Library: www.onsemi.com/design/resources/technical−documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support
For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales